

ductruong

* * * * * STN Columbus * * * * *

FILE 'HOME' ENTERED AT 10:34:06 ON 15 JUL 2009

=> file pnttext

COST IN U.S. DOLLARS

SINCE FILE

TOTAL

ENTRY

SESSION

FULL ESTIMATED COST

0.22

0.22

FILE 'EPFULL' ENTERED AT 10:34:41 ON 15 JUL 2009

COPYRIGHT (C) 2009 European Patent Office / FIZ Karlsruhe / LexisNexis Univentio

FILE 'FRFULL' ENTERED AT 10:34:41 ON 15 JUL 2009

COPYRIGHT (C) 2009 Univentio

FILE 'GBFULL' ENTERED AT 10:34:41 ON 15 JUL 2009

COPYRIGHT (C) 2009 Univentio

FILE 'PATDPFULL' ENTERED AT 10:34:41 ON 15 JUL 2009

COPYRIGHT (C) 2009 DPMA

FILE 'PCTFULL' ENTERED AT 10:34:41 ON 15 JUL 2009

COPYRIGHT (C) 2009 Univentio

FILE 'RDISCLOSURE' ENTERED AT 10:34:41 ON 15 JUL 2009

COPYRIGHT (C) 2009 Kenneth Mason Publications Ltd.

FILE 'USPATFULL' ENTERED AT 10:34:41 ON 15 JUL 2009

CA INDEXING COPYRIGHT (C) 2009 AMERICAN CHEMICAL SOCIETY (ACS)

FILE 'USPATOLD' ENTERED AT 10:34:41 ON 15 JUL 2009

CA INDEXING COPYRIGHT (C) 2009 AMERICAN CHEMICAL SOCIETY (ACS)

FILE 'USPAT2' ENTERED AT 10:34:41 ON 15 JUL 2009

CA INDEXING COPYRIGHT (C) 2009 AMERICAN CHEMICAL SOCIETY (ACS)

=> s shape memory resin#

L1 308 SHAPE MEMORY RESIN#

=> s l1 and glass transtion temperature

L2 0 L1 AND GLASS TRANSITION TEMPERATURE

=> s l1 and glass transition temperature

L3 124 L1 AND GLASS TRANSITION TEMPERATURE

=> s l3 and Tg and Td

L4 13 L3 AND TG AND TD

=> s l4 and thermoreversible

L5 2 L4 AND THERMOREVERSIBLE

=> d l5 1-2

L5 ANSWER 1 OF 2 PCTFULL COPYRIGHT 2009 Univentio on STN

AN 2005056642 PCTFULL ED 20050628 EW 200525

TIEN RESHAPABLE SHAPE-MEMORY RESIN EXCELLING IN

SHAPE RECOVERY CAPABILITY AND SHAPED ITEM OF THE RESIN HAVING BEEN
CROSSLINKED

TIFR RESINE A MEMOIRE DE FORME REFACONNABLE PRESENTANT UNE CAPACITE DE

ductruong

RECUPERATION DE FORME EXCELLENTE ET ARTICLE FORME CONSTITUE DE LA RESINE
 AYANT ETE RETICULEE

IN SHIMURA, Midori, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
 Tokyo 1088001, JP [JP, JP];
 INOUE, Kazuhiko, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
 Tokyo 1088001, JP [JP, JP];
 IJI, Masatoshi, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
 Tokyo 1088001, JP [JP, JP]

PA NEC CORPORATION, 7-1, Shiba 5-chome, Minato-ku, Tokyo 1088001, JP [JP,
 JP], for all designates States except US;
 SHIMURA, Midori, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
 Tokyo 1088001, JP [JP, JP], for US only;
 INOUE, Kazuhiko, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
 Tokyo 1088001, JP [JP, JP], for US only;
 IJI, Masatoshi, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
 Tokyo 1088001, JP [JP, JP], for US only

AG MIYAZAKI, Teruo, 8th Floor, 16th Kowa Bldg., 9-20, Akasaka 1-chome,
 Minato-ku, Tokyo 1070052, JP

LAF Japanese
 LA Japanese
 DT Patent
 PI WO 2005056642 A1 20050623
 DS W: AE AG AL AM AT AU AZ BA BB BG BR BW BY BZ CA CH CN CO CR
 CU CZ DE DK DM DZ EC EE EG ES FI GB GD GE GH GM HR HU ID
 IL IN IS JP KE KG KP KR KZ LC LK LR LS LT LU LV MA MD MG
 MK MN MW MX MZ NA NI NO NZ OM PG PH PL PT RO RU SC SD SE
 SG SK SL SY TJ TM TN TR TT TZ UA UG US UZ VC VN YU ZA ZM
 ZW
 W-U: AE AL AM AT AZ BG BR BY BZ CN CO CR CZ DE DK EC EE EG ES
 FI GE HU JP KE KG KP KR KZ LS MD MX MZ NI PH PL PT RU SK
 SL TJ TR TT UA UG UZ YU
 RW (ARIPO): BW GH GM KE LS MW MZ NA SD SL SZ TZ UG ZM ZW
 RW (EAPO): AM AZ BY KG KZ MD RU TJ TM
 RW (EPO): AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LT
 LU MC NL PL PT RO SE SI SK TR
 RW (OAPI): BF BJ CF CG CI CM GA GN GQ GW ML MR NE SN TD TG
 RW-U (OAPI): BF BJ CF CG CI CM GA GN GQ GW ML MR NE SN TD TG

PRAI JP 2003-2003-415258 20031212
 AI WO 2004-JP18490 A 20041210
 ICM C08G085-00
 ICS C08F008-00; C08G063-91; C08G064-42; C08L101-16

L5 ANSWER 2 OF 2 USPTATFULL on STN
 AN 2007:169785 USPTATFULL
 TI Shape-memory resin performing
 remoldability and excellent in shape recovering property, and molded
 product composed of the cross-linked resin

IN Shimura, Midori, Tokyo, JAPAN
 Inoue, Kazuhiko, Tokyo, JAPAN
 Iji, Masatoshi, Tokyo, JAPAN

PI US 20070148465 A1 20070628
 AI US 2004-582675 A1 20041210 (10)
 WO 2004-JP18490 20041210
 20060612 PCT 371 date

PRAI JP 2003-415258 20031212
 DT Utility
 FS APPLICATION
 LN.CNT 1487
 INCL INCLM: 428/411.100

ductruong

INCLS: 521/040.000
NCL NCLM: 428/411.100
NCLS: 521/040.000
IC IPCI B32B0009-04 [I,A]; C08J0011-04 [I,A]; C08J0011-00 [I,C*]
IPCR B32B0009-04 [I,C]; B32B0009-04 [I,A]; C08G0063-00 [I,C*];
C08G0063-08 [I,A]; C08G0063-91 [I,A]; C08J0011-00 [I,C];
C08J0011-04 [I,A]; C08K0005-00 [I,C*]; C08K0005-12 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> d 14 1-13

L4 ANSWER 1 OF 13 EPFULL COPYRIGHT 2009 EPO/FIZ KA/LNU on STN

AN 2003:99631 EPFULL
DUPD 20040526 DUPW 200422

TIEN SHAPE-MEMORY LAMINATED POLYBUTYLENE TEREPHTHALATE FILM, PRODUCTION
PROCESS AND USE THEREOF, AND PROCESS FOR PRODUCTION OF POLYBUTYLENE
TEREPHTHALATE FILM.

TIFR FILM LAMINE DE TEREPHTHALATE DE POLYBUTYLENE A MEMOIRE DE FORME, SON
PROCEDE DE FABRICATION, SES UTILISATIONS, ET PROCEDE DE PRODUCTION DE
FILMS DE TEREPHTHALATE DE POLYBUTYLENE.

IN Kagawa, Seiji, 304, 252-1, Akayama-cho 1-chome, Koshigaya-shi, Saitama
343-0807, JP

PA Kagawa, Seiji, 304, 252-1, Akayama-cho 1-chome, Koshigaya-shi, Saitama
343-0807, JP

PAN 1368996
DT Patent
LAF Japanese
LA English
LAP English
TL English; French

PIT WO/1 International application published with search report
PI WO 2004026577 A1 20040401

DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE
SI SK TR
EXTENSION STATES: AL LT LV MK

AI EP 2003-797727 A 20030922
WO 2003-JP12102 A 20030922

PRAI JP 2002-275939 A 20020920
JP 2003-1533 A 20030107
JP 2003-1534 A 20030107

IC.VER 7
ICM B32B027-36
ICS B29C055-28

AN 2003:99631 EPFULL ED 20050629 UP 20090218
DUPD 20090218 DUPW 200908

TIEN SHAPE-MEMORY LAMINATED POLYBUTYLENE TEREPHTHALATE FILM, PRODUCTION
PROCESS AND USE THEREOF, AND PROCESS FOR PRODUCTION OF POLYBUTYLENE
TEREPHTHALATE FILM.

TIFR FILM LAMINE DE TEREPHTHALATE DE POLYBUTYLENE A MEMOIRE DE FORME, SON
PROCEDE DE FABRICATION, SES UTILISATIONS, ET PROCEDE DE PRODUCTION DE
FILMS DE TEREPHTHALATE DE POLYBUTYLENE.

TIDE LAMINIERTE POLYBUTYLENTEREPHTHALAT-FORMGEDAeCHTNISFOLIE,
HERSTELLUNGSVERFAHREN UND VERWENDUNG DAVON SOWIE VERFAHREN ZUR
HERSTELLUNG DER POLYBUTYLENTEREPHTHALATFOLIE.

IN KAWAGA, Seiji, 202, 252-1, Akayama-cho 1-chome, Koshigaya-shi, Saitama
343-0807, JP

ductruong

PA Kagawa, Seiji, 202, 252-1, Akayama-cho 1-chome, Koshigaya-shi, Saitama
343-0807, JP
PAN 1368997
AG Strehl Schuebel-Hopf & Partner, Maximilianstrasse 54, 80538 Muenchen, DE
AGN 100941
DT Patent
LAF Japanese
LA English
LAP English
TL German; English; French
PIT EPat Application published with search report
PI EP 1547767 A1 20050629
WO 2004026577 20040401
DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE
SI SK TR
AI EP 2003-797727 A 20030922
WO 2003-JP12102 A 20030922
PRAI JP 2002-275939 A 20020920
JP 2003-1533 A 20030107
JP 2003-1534 A 20030107
IPCI B32B0027-36 [I,A]; B29C0047-00 [I,A]; B29C0055-28 [I,A]
B32B0027-36 [I,C*]; B29C0047-00 [I,C*]; B29C0055-28 [I,C*]
L4 ANSWER 2 OF 13 EPFULL COPYRIGHT 2009 EPO/FIZ KA/LNU on STN
AN 2003:99613 EPFULL
DUPD 20040526 DUPW 200422
TIEN METHOD AND APPARATUS FOR PRODUCING POLYBUTYLENE TEREPHTHALATE FILM, AND
SHAPE-MEMORY POLYBUTYLENE TEREPHTHALATE LAMINATED FILM.
TIFR PROCEDE ET APPAREIL DE PRODUCTION D'UN FILM DE TEREPHTALATE DE
POLYBUTYLENE, ET FILM LAMINE DE TEREPHTALATE DE POLYBUTYLENE A MEMOIRE
DE FORME.
IN Kagawa, Seiji, 304, 252-1, Akayama-cho 1-chome, Koshigaya-shi, Saitama
343-0807, JP
PA Kagawa, Seiji, 304, 252-1, Akayama-cho 1-chome, Koshigaya-shi, Saitama
343-0807, JP
PAN 1368996
DT Patent
LAF Japanese
LA English
LAP English
TL English; French
PIT WOAI International application published with search report
PI WO 2004026558 A1 20040401
DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE
SI SK TR
EXTENSION STATES: AL LT LV MK
AI EP 2003-797728 A 20030922
WO 2003-JP12103 A 20030922
PRAI JP 2002-275939 A 20020920
JP 2003-1533 A 20030107
JP 2003-1534 A 20030107
JP 2003-122785 A 20030425
IC.VER 7
ICM B29C047-00
ICS B29C055-28; B32B027-36
ICI B29K067:00
AN 2003:99613 EPFULL ED 20050629 UP 20060218

ductruong

DUPD 20060125 DUPW 200604

TIEN METHOD AND APPARATUS FOR PRODUCING POLYBUTYLENE TEREPHTHALATE FILM, AND
SHAPE-MEMORY POLYBUTYLENE TEREPHTHALATE LAMINATED FILM.

TIFR PROCEDE ET APPAREIL DE PRODUCTION D'UN FILM DE TEREPHTALATE DE
POLYBUTYLENE, ET FILM LAMINE DE TEREPHTALATE DE POLYBUTYLENE A MEMOIRE
DE FORME.

TIDE VERFAHREN UND VORRICHTUNG ZUR HERSTELLUNG EINER
POLYBUTYLENTEREPHTHALAT-FOLIE UND LAMINIERT
POLYBUTYLENTEREPHTHALAT-FORMGEDAECHTNISFOLIE.

IN Kagawa, Seiji, 202, 252-1, Akayama-cho 1-chome, Koshigaya-shi, Saitama
343-0807, JP

PA Kagawa, Seiji, 202, 252-1, Akayama-cho 1-chome, Koshigaya-shi, Saitama
343-0807, JP

PAN 1368997

AG Strehl Schuebel-Hopf & Partner, Maximilianstrasse 54, 80538 Muenchen, DE

AGN 100941

DT Patent

LAF Japanese

LA English

LAP English

TL German; English; French

PIT EPAL Application published with search report

PI EP 1547750 A1 20050629

WO 2004026558 20040401

DS AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE
SI SK TR

AI EP 2003-797728 A 20030922

WO 2003-JP12103 A 20030922

PRAI JP 2002-275939 A 20020920

JP 2003-1533 A 20030107

JP 2003-1534 A 20030107

JP 2003-122785 A 20030425

IPCI B29C0047-00 [I,A]; B29C0055-28 [I,A]; B32B0027-36 [I,A];
B29K0067-00 [I,A]
B29C0047-00 [I,C*]; B29C0055-28 [I,C*]; B32B0027-36 [I,C*];
B29K0067-00 [I,C*]

L4 ANSWER 3 OF 13 EFPULL COPYRIGHT 2009 EPO/FIZ KA/LNU on STN

AN 2001:50072 EFPULL

DUPD 20020102 DUPW 200201

TIEN MOLDED OBJECT OF THERMOPLASTIC RESIN AND COMPOSITION.

TIFR OBJET MOULE EN RESINE THERMOPLASTIQUE ET COMPOSITION.

IN HIROSE, Toshiyuki, c/o Mitsui Chemicals, Inc., 1-2, Waki 6-chome,
Waki-cho, Kuga-gun, Yamaguchi 740-0061, JP;
MAENO, Masao, c/o Mitsui Chemicals, Inc., 1-2, Waki 6-chome, Waki-cho,
Kuga-gun, Yamaguchi 740-0061, JP

PA Mitsui Chemicals, Inc., 2-5, Kasumigaseki 3-chome, Chiyoda-ku, Tokyo
100-6070, JP

PAN 213645

DT Patent

LAF Japanese

LA English

LAP English

TL English; French

PIT WOAI International application published with search report

PI WO 2001083612 A1 20011108

DS DE FR GB

EXTENSION STATES: AL LT LV MK RO SI

ductruong

AI	EP 2001-926034	A	20010427		
	WO 2001-JP3709	A	20010427		
PRAI	JP 2000-131245	A	20000428		
	JP 2000-131700	A	20000428		
IC.VER	7				
ICM	C08L023-26				
ICS	C08J005-18				
AN	2001:50072	EPFULL	UP	20061005	
	DUPD 20061004	DUPW	200640		
TIEN	MOLDED OBJECT OF THERMOPLASTIC RESIN AND COMPOSITION.				
TIFR	OBJET MOULE EN RESINE THERMOPLASTIQUE ET COMPOSITION.				
TIDE	GEFORMTER GEGENSTAND AUS EINEM THERMOPLASTISCHEN HARZ UND ZUSAMMENSETZUNG.				
IN	HIROSE, Toshiyuki, c/o Mitsui Chemicals, Inc., 1-2, Waki 6-chome, Waki-cho, Kuga-gun, Yamaguchi 740-0061, JP; MAENO, Masao, c/o Mitsui Chemicals, Inc., 1-2, Waki 6-chome, Waki-cho, Kuga-gun, Yamaguchi 740-0061, JP				
PA	Mitsui Chemicals, Inc., 5-2, Higashi-Shimbashi 1-Chome Minato-ku, Tokyo, JP				
PAN	5013870				
AG	HOFFMANN EITLE, Patent- und Rechtsanwaelte Arabellastrasse 4, 81925 Muenchen, DE				
AGN	101511				
DT	Patent				
LAF	Japanese				
LA	English				
LAP	English				
TL	German; English; French				
PIT	EPA1 Application published with search report				
PI	EP 1234854	A1	20020828		
	WO 2001083612		20011108		
DS	DE FR GB				
AI	EP 2001-926034	A	20010427		
	WO 2001-JP3709	A	20010427		
PRAI	JP 2000-131245	A	20000428		
	JP 2000-131700	A	20000428		
IPCI	C08L0023-08	[I,A]	C08L0065-00	[I,A]	B32B0027-32 [I,A]
	C08L0023-00	[I,C*]	C08L0065-00	[I,C*]	B32B0027-32 [I,C*]
AN	2001:50072	EPFULL	ED	20070110	UP 20071219
	DUPD 20071219	DUPW	200751		
TIEN	MOLDED OBJECT OF THERMOPLASTIC RESIN AND COMPOSITION.				
TIFR	OBJET MOULE EN RESINE THERMOPLASTIQUE ET COMPOSITION.				
TIDE	GEFORMTER GEGENSTAND AUS EINEM THERMOPLASTISCHEN HARZ UND ZUSAMMENSETZUNG.				
IN	HIROSE, Toshiyuki, c/o Mitsui Chemicals, Inc., 1-2, Waki 6-chome, Waki-cho, Kuga-gun, Yamaguchi 740-0061, JP; MAENO, Masao, c/o Mitsui Chemicals, Inc., 1-2, Waki 6-chome, Waki-cho, Kuga-gun, Yamaguchi 740-0061, JP				
PA	Mitsui Chemicals, Inc., 5-2, Higashi-Shimbashi 1-Chome Minato-ku, Tokyo, JP				
PAN	5013870				
AG	HOFFMANN EITLE, Patent- und Rechtsanwaelte Arabellastrasse 4, 81925 Muenchen, DE				
AGN	101511				
DT	Patent				
LAF	Japanese				
LA	English				

ductruong

LAP	English			
TL	German; English; French			
PIT	EPB1 Granted patent			
PI	EP 1234854	B1	20070110	
	WO 2001083612		20011108	
DS	DE FR GB			
AI	EP 2001-926034	A	20010427	
	WO 2001-JP3709	A	20010427	
PRAI	JP 2000-131245	A	20000428	
	JP 2000-131700	A	20000428	
REP	EP 1270203	A	(INID56)	
	WO 2000066357	A	(INID56)	
	WO 9613530	A1	(INID56)	
	GB 1113409	A	(INID56)	
	JP 5271489	A	(INID56)	
	JP 8165357	A	(INID56)	
	JP 8267679	A	(INID56)	
	JP 62257341	A	(INID56)	
	JP 2000086778	A	(INID56)	
	JP 2000159946	A	(INID56)	
IPCI	C08L0023-08	[I,A];	C08L0065-00	[I,A]; B32B0027-32 [I,A]
	C08L0023-00	[I,C*];	C08L0065-00	[I,C*]; B32B0027-32 [I,C*]
L4	ANSWER 4 OF 13	PCTFULL	COPYRIGHT 2009 Univentio on STN	
AN	2008075844	PCTFULL	ED 20080704	
		UP	20080704 (full-text)	
TIEN	SHAPE MEMORY POLYAMIDE AND METHOD OF PRODUCING SHAPE MEMORY POLYAMIDE			
	FABRIC USING THE SAME			
TIFR	POLYAMIDE A MEMOIRE DE FORME ET PROCEDE DE PRODUCTION D'UN TISSU EN			
	POLYAMIDE A MEMOIRE DE FORME UTILISANT CE POLYAMIDE			
IN	KIM, Chang Woo, 1004-805, Hyosung Apartment Anyang-9dong, Anyang-si			
	Gyeonggi-do 430-019, KR			
PA	HYOSUNG CORPORATION, 450, Kongduk-dong Mapo-gu Seoul 121-120, KR;			
	KIM, Chang Woo, 1004-805, Hyosung Apartment Anyang-9dong, Anyang-si			
	Gyeonggi-do 430-019, KR			
AG	KIM, Hak Je et al., Phoenix International Patent and Law Office			
	Kwanghwamoon P.O. Box 1828 Seoul 110-618, KR			
LA	English			
DT	Patent			
PI	WO 2008075844	A1	20080626	
DS	W:			
	AE AG AL AM AT AU AZ BA BB BG BH BR BW BY BZ CA CH CN CO			
	CR CU CZ DE DK DM DO DZ EC EE EG ES FI GB GD GE GH GM GT			
	HN HR HU ID IL IN IS JP KE KG KM KN KP KZ LA LC LK LR LS			
	LT LU LY MA MD ME MG MK MN MW MX MY MZ NA NG NI NO NZ OM			
	PG PH PL PT RO RS RU SC SD SE SG SK SL SM SV SY TJ TM TN			
	TR TT TZ UA UG US UZ VC VN ZA ZM ZW			
	RW (ARIPO): BW GH GM KE LS MW MZ NA SD SL SZ TZ UG ZM ZW			
	RW (EAP): AM AZ BY KG KZ MD RU TJ TM			
	RW (EPO): AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LT			
	LU LV MC MT NL PL PT RO SE SI SK TR			
	RW (OAPI): BF BJ CF CG CI CM GA GN GQ GW ML MR NE SN TD TG			
PRAI	KR 2006-1020060130793		20061220	
	KR 2007-1020070109460		20071030	
AI	WO 2007-KR6320	A	20071206	
IPCI	C08G0069-32 [I,A]			
	C08G0069-00 [I,C*]			
L4	ANSWER 5 OF 13	PCTFULL	COPYRIGHT 2009 Univentio on STN	
AN	2005056642	PCTFULL	ED 20050628 EW 200525	

ductruong

TIEN RESHAPABLE SHAPE-MEMORY RESIN EXCELLING IN
SHAPE RECOVERY CAPABILITY AND SHAPED ITEM OF THE RESIN HAVING BEEN
CROSSLINKED

TIFR RESINE A MEMOIRE DE FORME REFACONNABLE PRESENTANT UNE CAPACITE DE
RECUPERATION DE FORME EXCELLENTE ET ARTICLE FORME CONSTITUE DE LA RESINE
AYANT ETE RETICULEE

IN SHIMURA, Midori, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
Tokyo 1088001, JP [JP, JP];
INOUE, Kazuhiko, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
Tokyo 1088001, JP [JP, JP];
IJI, Masatoshi, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
Tokyo 1088001, JP [JP, JP]

PA NEC CORPORATION, 7-1, Shiba 5-chome, Minato-ku, Tokyo 1088001, JP [JP,
JP], for all designates States except US;
SHIMURA, Midori, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
Tokyo 1088001, JP [JP, JP], for US only;
INOUE, Kazuhiko, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
Tokyo 1088001, JP [JP, JP], for US only;
IJI, Masatoshi, c/o NEC Corporation, 7-1, Shiba 5-chome, Minato-ku,
Tokyo 1088001, JP [JP, JP], for US only

AG MIYAZAKI, Teruo, 8th Floor, 16th Kowa Bldg., 9-20, Akasaka 1-chome,
Minato-ku, Tokyo 1070052, JP

LAF Japanese
LA Japanese
DT Patent
PI WO 2005056642 A1 20050623
DS W: AU AG AL AM AT AU AZ BA BB BG BR BW BY BZ CA CH CN CO CR
CU CZ DE DK DM DZ EC EE EG ES FI GB GD GE GH GM HR HU ID
IL IN IS JP KE KG KP KR KZ LC LR LS LT LU LV MA MD MG
MK MN MW MX MZ NA NI NO NZ OM PG PH PL PT RO RU SC SD SE
SG SK SL SY TJ TM TN TR TT TZ UA UG US UZ VC VN YU ZA ZM
ZW
W-U: AE AL AM AT AZ BG BR BY BZ CN CO CR CZ DE DK EC EE EG ES
FI GE HU JP KE KG KP KR KZ LS MD MX MZ NI PH PL PT RU SK
SL TJ TR TT UA UG UZ YU
RW (ARIPO): BW GH GM KE LS MW MZ NA SD SL SZ TZ UG ZM ZW
RW (EAPO): AM AZ BY KG KZ MD RU TJ TM
RW (EPO): AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LT
LU MC NL PL PT RO SE SI SK TR
RW (OAPI): BF BJ CF CG CI CM GA GN GQ GW ML MR NE SN TD TG
RW-U (OAPI): BF BJ CF CG CI CM GA GN GQ GW ML MR NE SN TD TG

PRAI JP 2003-2003-415258 20031212
AI WO 2004-JP18490 A 20041210
ICM C08G085-00
ICS C08F008-00; C08G063-91; C08G064-42; C08L101-16

L4 ANSWER 6 OF 13 USPTATFULL on STN
AN 2007:169785 USPTATFULL
TI Shape-memory resin performing
remoldability and excellent in shape recovering property, and molded
product composed of the cross-linked resin

IN Shimura, Midori, Tokyo, JAPAN
Inoue, Kazuhiko, Tokyo, JAPAN
Iji, Masatoshi, Tokyo, JAPAN

PI US 20070148465 A1 20070628
AI US 2004-582675 A1 20041210 (10)
WO 2004-JP18490 20041210
20060612 PCT 371 date

PRAI JP 2003-415258 20031212

ductruong

DT Utility
FS APPLICATION
LN.CNT 1487
INCL INCLM: 428/411.100
INCLS: 521/040.000
NCL NCLM: 428/411.100
NCLS: 521/040.000
IC IPCI B32B0009-04 [I,A]; C08J0011-04 [I,A]; C08J0011-00 [I,C*]
IPCR B32B0009-04 [I,C]; B32B0009-04 [I,A]; C08G0063-00 [I,C*];
C08G0063-08 [I,A]; C08G0063-91 [I,A]; C08J0011-00 [I,C];
C08J0011-04 [I,A]; C08K0005-00 [I,C*]; C08K0005-12 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L4 ANSWER 7 OF 13 USPTFULL on STN
AN 2006:67187 USPTFULL
TI Method and apparatus for producing polybutylene terephthalate film, and
shape-memory polybutylene terephthalate laminate film
IN Kagawa, Seiji, Saitama-ken, JAPAN
PI US 20060057405 A1 20060316
AI US 2003-528366 A1 20030922 (10)
WO 2003-JP12103 20030922
20050318 PCT 371 date
PRAI JP 2002-275939 20020920
JP 2003-1533 20030107
JP 2003-1534 20030107
JP 2003-122785 20030425

DT Utility
FS APPLICATION
LN.CNT 2531
INCL INCLM: 428/458.000
INCLS: 428/480.000; 428/481.000
NCL NCLM: 428/458.000
NCLS: 428/480.000; 428/481.000
IC IPCI B32B0027-36 [I,A]; B32B0027-10 [I,A]; B32B0015-08 [I,A]
IPCR B32B0027-36 [I,A]; B29C0035-00 [N,C*]; B29C0035-16 [N,A];
B29C0047-00 [N,C*]; B29C0047-00 [N,A]; B29C0047-06 [I,C*];
B29C0047-06 [I,A]; B29C0047-88 [I,C*]; B29C0047-88 [I,A];
B29C0047-90 [N,C*]; B29C0047-90 [N,A]; B29C0047-92 [I,C*];
B29C0047-92 [I,A]; B29C0055-28 [I,C*]; B29C0055-28 [I,A];
B29C0061-06 [I,C*]; B29C0061-06 [I,A]; B32B0015-08 [I,C];
B32B0015-08 [I,A]; B32B0027-06 [I,C*]; B32B0027-06 [I,A];
B32B0027-10 [I,C]; B32B0027-10 [I,A]; B32B0027-36 [I,C];
B32B0037-12 [N,C*]; B32B0037-12 [N,A]; B32B0037-14 [I,C*];
B32B0037-15 [N,A]; B32B0037-20 [I,A]; B65D0077-10 [I,C*];
B65D0077-20 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L4 ANSWER 8 OF 13 USPTFULL on SIN
AN 2006:60375 USPTFULL
TI Shape-memory polybutylene terephthalate film, production process and use
thereof, and process for production of polybutylene terephthalate film
IN Kagawa, Seiji, Saitama-ken, JAPAN
PI US 20060051540 A1 20060309
AI US 2003-528371 A1 20030922 (10)
WO 2003-JP12102 20030922
20050318 PCT 371 date
PRAI JP 2002-275939 20020920
JP 2003-1533 20030107
JP 2003-1534 20030107

ductruong

DT Utility
FS APPLICATION
LN.CNT 2652
INCL INCLM: 428/035.700
INCLS: 428/043.000
NCL NCLM: 428/035.700
NCLS: 428/043.000
IC IPCI B32B0027-08 [I,A]
IPCR B32B0027-08 [I,A]; B29C0035-00 [N,C*]; B29C0035-16 [N,A];
B29C0047-00 [N,C*]; B29C0047-00 [N,A]; B29C0047-06 [I,C*];
B29C0047-06 [I,A]; B29C0047-88 [I,C*]; B29C0047-88 [I,A];
B29C0047-90 [N,C*]; B29C0047-90 [N,A]; B29C0047-92 [I,C*];
B29C0047-92 [I,A]; B29C0055-28 [I,C*]; B29C0055-28 [I,A];
B29C0061-06 [I,C*]; B29C0061-06 [I,A]; B32B0027-08 [I,C];
B32B0037-12 [N,C*]; B32B0037-12 [N,A]; B32B0037-14 [I,C*];
B32B0037-15 [N,A]; B32B0037-20 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L4 ANSWER 9 OF 13 USPATFULL on STN
AN 2002:343774 USPATFULL
TI Molded object of thermoplastic resin and composition
IN Hirose, Toshiyuki, Yamaguchi-ken, JAPAN
Maeno, Masao, Yamaguchi-ken, JAPAN
PI US 20020197499 A1 20021226
US 6709761 B2 20040323
AI US 2001-19221 A1 20011228 (10)
WO 2001-JP3709 20010727
PRAI JP 2000-131245 20000428
JP 2000-131700 20000428
DT Utility
FS APPLICATION
LN.CNT 1291
INCL INCLM: 428/517.000
INCLS: 428/910.000; 428/520.000
NCL NCLM: 428/517.000
NCLS: 428/520.000; 428/522.000; 428/910.000; 525/191.000; 525/216.000;
525/221.000; 525/240.000; 525/241.000
IC [7]
ICM B32B027-08
IPCI B32B0027-08 [ICM,7]
IPCI-2 B32B0027-32 [ICM,7]; C08J0005-18 [ICS,7]; C08L0023-26 [ICS,7];
C08L0023-00 [ICS,7,C*]
IPCR C08L0023-00 [I,C*]; C08L0023-08 [I,A]; C08L0065-00 [I,C*];
C08L0065-00 [I,A]
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L4 ANSWER 10 OF 13 USPATFULL on STN
AN 2001:146875 USPATFULL
TI Image-forming system
IN Suzuki, Minoru, Tochigi, Japan
Orita, Hiroshi, Saitama, Japan
Saito, Hiroyuki, Saitama, Japan
Suzuki, Katsuyoshi, Tokyo, Japan
Furusawa, Koichi, Tokyo, Japan
PA Asahi Kogaku Kogyo Kabushiki Kaisha, Tokyo, Japan (non-U.S. corporation)
PI US 6283649 B1 20010904
AI US 2000-599850 20000623 (9)
RLI Continuation of Ser. No. US 1999-263260, filed on 5 Mar 1999, now
patented, Pat. No. US 6106173

ductruong

PRAI JP 1998-73454 19980306
DT Utility
FS GRANTED
LN.CNT 611
INCL INCLM: 400/120.010
INCLS: 400/120.020; 400/124.080; 400/124.090; 400/149.000; 347/171.000;
347/172.000
NCL NCLM: 400/120.010
NCLS: 347/171.000; 347/172.000; 400/120.020; 400/124.080; 400/124.090;
400/149.000
IC [7]
ICM B41J002-32
IPCI B41J0002-32 [ICM,7]
IPCR B41J0002-32 [I,A]; B41J0002-32 [I,C*]
EXF 400/120.01; 400/120.05; 400/120.06; 400/120.07; 400/120.08; 400/120.09;
400/120.1; 400/120.11; 400/120.12; 400/120.13; 400/120.14; 400/120.15;
400/124.08; 400/124.09; 400/124.11; 400/124.12; 400/124.13; 400/124.14;
400/124.15; 400/149; 400/120.02-120.04; 347/171; 347/172; 347/180;
347/181; 347/182; 347/188; 347/189; 347/190; 347/191; 347/192
L4 ANSWER 11 OF 13 USPATFULL on STN
AN 2001:54821 USPATFULL
TI Temperature control apparatus
IN Orita, Hiroshi, Saitama, Japan
Suzuki, Minoru, Tochigi, Japan
Saito, Hiroyuki, Saitama, Japan
Suzuki, Katsuyoshi, Tokyo, Japan
Furusawa, Koichi, Tokyo, Japan
PA Asahi Kogaku Kogyo Kabushiki Kaisha, Tokyo, Japan (non-U.S. corporation)
PI US 6217239 B1 20010417
AI US 1999-275422 19990324 (9)
PRAI JP 1998-96590 19980325
DT Utility
FS Granted
LN.CNT 689
INCL INCLM: 400/120.010
INCLS: 400/120.020; 400/120.140; 347/171.000; 347/172.000; 347/191.000;
347/194.000
NCL NCLM: 400/120.010
NCLS: 347/171.000; 347/172.000; 347/191.000; 347/194.000; 400/120.020;
400/120.140
IC [7]
ICM B41J002-315
IPCI B41J0002-315 [ICM,7]
IPCR B41J0002-32 [I,A]; B41J0002-32 [I,C*]; B41J0002-365 [I,A];
B41J0002-365 [I,C*]
EXF 400/120.01; 400/120.02; 400/120.14; 347/194; 347/191; 347/171; 347/172;
347/5; 347/17
L4 ANSWER 12 OF 13 USPATFULL on STN
AN 2000:108684 USPATFULL
TI Image-forming system including a plurality of thermal heads and an
image-forming sheet with a plurality of types of micro-capsules
IN Suzuki, Minoru, Tochigi, Japan
Orita, Hiroshi, Saitama, Japan
Saito, Hiroyuki, Saitama, Japan
Suzuki, Katsuyoshi, Tokyo, Japan
Furusawa, Koichi, Tokyo, Japan
PA Asahi Kogaku Kogyo Kabushiki Kaisha, Tokyo, Japan (non-U.S. corporation)

ductruong

PI US 6106173 20000822
AI US 1999-263260 19990305 (9)
PRAI JP 1998-73454 19980306
DT Utility
FS Granted
LN.CNT 616
INCL INCLM: 400/120.020
INCLS: 400/241.200; 400/149.000; 400/082.000; 347/172.000; 347/173.000
NCL NCLM: 400/120.020
NCLS: 347/172.000; 347/173.000; 400/082.000; 400/149.000; 400/241.200
IC [7]
ICM B41J002-32
ICS B41J003-54
IPCI B41J0002-32 [ICM,7]; B41J0003-54 [ICS,7]
IPCR B41J0002-32 [I,A]; B41J0002-32 [I,C*]
EXF 347/212; 347/172; 347/173; 400/241.2; 400/120.01; 400/120.02;
400/120.04; 400/124.08; 400/124.09; 400/124.1; 400/149; 400/82;
428/321.5

L4 ANSWER 13 OF 13 USPAT2 on STN
AN 2002:343774 USPAT2
TI Molded object of thermoplastic resin and composition
IN Hirose, Toshiyuki, Yamaguchi-ken, JAPAN
PA Maeno, Masao, Yamaguchi-ken, JAPAN
Mitsui Chemicals, Inc., Tokyo, JAPAN (non-U.S. corporation)
PI US 6709761 B2 20040323
WO 2001083612 20011108
AI US 2001-19221 20011228 (10)
WO 2001-JP3709 20010427
PRAI JP 2000-131245 20000428
JP 2000-131700 20000428
DT Utility
FS GRANTED
LN.CNT 1274
INCL INCLM: 428/517.000
INCLS: 428/520.000; 428/522.000; 428/910.000; 525/191.000; 525/216.000;
525/221.000; 525/240.000; 525/241.000
NCL NCLM: 428/517.000
NCLS: 428/520.000; 428/522.000; 428/910.000; 525/191.000; 525/216.000;
525/221.000; 525/240.000; 525/241.000
IC [7]
ICM B32B027-32
ICS C08J005-18; C08L023-26
IPCI B32B0027-08 [ICM,7]
IPCI-2 B32B0027-32 [ICM,7]; C08J0005-18 [ICS,7]; C08L0023-26 [ICS,7];
C08L0023-00 [ICS,7,C*]
IPCR C08L0023-00 [I,C*]; C08L0023-08 [I,A]; C08L0065-00 [I,C*];
C08L0065-00 [I,A]
EXF 428/517; 428/520; 428/522; 428/910; 525/191; 525/216; 525/221; 525/240;
525/241
CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=>